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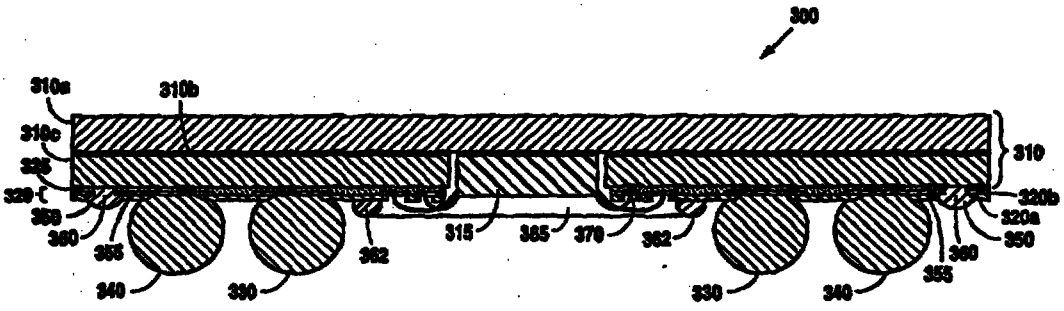
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(54) Title: TAB TAPE BALL GRID ARRAY PACKAGE WITH VIAS LATERALLY OFFSET FROM SOLDER BALL BOND SITES



(57) Abstract

A ball grid array (BGA) package is provided in which the stiffener of the BGA may also be utilized as a conductive layer. A TAB tape is adhered to the stiffener by an adhesive and both the TAB tape and the adhesive may have vias which open to the stiffener. Conductive plugs which may be formed of solder paste, conductive adhesives, or the like may then be filled in the vias to provide electrical connection from the TAB tape to the stiffener. The vias may be located adjacent to solder ball locations. The TAB tape may include multiple conductor layers or multiple layers of single conductive layer TAB tape may be stacked upon each other to provide additional circuit routing. Further, the TAB tape layers may also be combined with the use of metal foil layers.